

- two Bondmachines are waiting to be shipped --> We envision to ship these together with other items in November
- prototype FEB8-N 30 pieces --> pcbs arrived and will be populated with passives
- prototype FEB8-P 30 pieces --> pcbs not delivered yet, planned for first week November, then population with parts.
- Bonding Needles --> available
- Special Sensors --> ordered but delivery earliest January
- HV-LV rad tolerant MPD --> tender ongoing, latest adjustments on items with Sergeij Movchan on the weekend
- Digital Microscope --> available, will be sent to JINR with bonding machines in November
- VMM3a 34 wafers --> in production and almost through, I can now discuss with Fraunhofer on how to dice the chips. How thick should they be thinned?
- Climate Chamber with additional coolers --> Will be delivered in November, I intend to ship with bonding machines and microscope in November
- LDOs 1.2V, 1.8V --> approximately 1500 of each kind can be shipped with bonding machines
- BM@N micro cables --> first 12 masks printed and delivered yesterday to GSI. We ship these to LTU and they start production
- GERI Boards --> first 15 pieces ordered, but delivery time till May 2022

NICA-5 Stochastic cooling:

9 out of 15 broadband amplifiers are being sent to GSI. They will be shipped to JINR together with bonding machines.

open items: Cooling systems for BM@N and MPD --> Rudi should report.